

Atty Docket No.: JCLA6831

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active surface provided with a plurality of bonding pads;

forming a bump on each bonding pad;

providing a plurality of individual substrates, wherein each substrate includes at least a package unit, each package unit having a plurality of contact pads thereon;

respectively mounting the substrates onto the wafer such that each package unit corresponds to each chip and the contact pads are respectively connected to the corresponding bumps, wherein two neighboring substrates are separated by a gap;

filling an underfill material between the substrates and the wafer, wherein the underfill material is introduced through the gaps between the substrates and from the boundary of the wafer;

solidifying the underfill material; and

dicing the wafer and the substrates to form a plurality of individualized packages, each individualized package including one chip and one package unit.

7. (Once Amended) A flip chip packaging process comprising:

providing a wafer having a plurality of chips formed thereon, wherein each chip has an

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active surface provided with a plurality of bonding pads;

providing a plurality of individual substrates, wherein each substrate includes at least a package unit, the package unit having a plurality of contact pads thereon;

forming a bump on each contact pad;

respectively mounting the substrates onto the wafer such that each package unit corresponds to one chip and the bonding pads are respectively connected to the corresponding bumps,

wherein two neighboring substrates are separated by a gap;

filling an underfill material between the substrates and the wafer, wherein the underfill material is introduced through the gaps between the substrates and from the boundary of the wafer;

solidifying the underfill material; and

dicing the wafer and the substrates to form a plurality of individualized packages, each individualized package including one package unit and one chip.